Notes:

REVA

1. Need to break Inductor pad into 4 to accomediate GaN PL backup solution.

2. Tie Vbat- and SGND together only at LM5177 pin 30 and PAD.

3. Inductor sample provided by customer

4. GaN team to recommend HB1 and HB2 diodes

5. BSC devices on bottom side, Heatsink? Increase current capability?

REVB

1. Replace LMG2100 to LMG3100 for reduce the power losses dut to lower Rds_on.

2. Add snubber and Zener Diode for reduce the under shoot on SW.

3. Add pull-low resistor on PWMs.

4. Change High side PWM from HO.

5. Add RC filter to PWM output.

Feedback signal comes from main board

***. Tie Vbat- and SGND together only at LM5177 pin 30 and PAD.**

CAUTION HOT SURFACE

PCB Number: PMP23377
PCB Rev: B

PCB LOGO Pb-Free Symbol

PCB LOGO WEEE logo

PCB LOGO FCC disclaimer

Orderable:	Designed for: Public Release	Mod. Date: 2024/3/27
TID #: N/A	Project Title: 4-sw Buck Boost	
Number: PMP23377 Rev: B	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP23377B_BlankSheet.SchDoc	Size: B
Engineer: Richard Yin	Contact: http://www.ti.com/support	

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